

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yasuo Kohsaka et al.

Serial No.: 09/165,743

Filed: October 6, 1998

For: Mo-W MATERIAL FOR  
FORMATION OF WIRING,  
Mo-W TARGET AND METHOD  
FOR PRODUCTION THEREOF,  
AND Mo-W WIRING THIN FILM



Group Art Unit: 1648

Examiner: L. Scheiner

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OCT 12 1999

TECH CENTER 1600/2900

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

AMENDMENT

In reply to the Office Action mailed July 9, 1999, please amend the above-identified patent application as follows:

IN THE CLAIMS

Please add the following new claims:

- <sup>4</sup>21. The Mo-W wiring thin film according to claim <sup>1</sup>18,  
wherein the content of oxygen in the wiring thin film is not more than 500 ppm.
- <sup>5</sup>22. The Mo-W wiring thin film according to claim <sup>1</sup>18,  
wherein the content of oxygen in the wiring thin film is not more than 200 ppm.
- <sup>6</sup>23. The Mo-W wiring thin film according to claim <sup>1</sup>18;

LAW OFFICES

FINNEGAN, HENDERSON,  
FARABOW, GARRETT  
& DUNNER, L.L.P.  
STANFORD RESEARCH PARK  
700 HANSEN WAY  
PALO ALTO, CALIF. 94304  
650-849-6800